

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10594244			
<b>Filing Date:</b>	25-Sep-2006			
<b>Title of Invention:</b>	PROCESS FOR FORMING A SOLDER MASK, APPARATUS THEREOF AND PROCESS FOR FORMING ELECTRIC-CIRCUIT PATTERNED INTERNAL DIELECTRIC LAYER			
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<b>Filer:</b>	Marvin Jay Spivak/Sinee Samla			
<b>Attorney Docket Number:</b>	295770US40X PCT			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1810